

**Amendments to the Claims:**

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

**Listing of Claims:**

1. (Currently Amended) A method for producing a conductive coating on an insulating substrate, comprising:

equipping, in selected regions, at least one surface of an electrically insulating substrate with a coating of an electrically highly conductive first metal, the coating being structured as conductor paths a printed circuit board;

cleaning the at least one coated surface;

seeding the coating with seeds of a second metal;

depositing a layer including an alloy of the second metal onto the coating seeded with the seeds of the second metal; and

firing the substrate deposited with the layer of the second metal; and  
contacting a gold bonding wire to the first metal, wherein:

the substrate includes one of a ceramic and an LTCC,

the first metal includes silver, and

the second metal includes palladium.

2. (Canceled)

3. (Canceled)

4. (Currently Amended) The method as recited in Claim 1 3, wherein:

in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy.

5. (Currently Amended) The method as recited in Claim 1 3, wherein:

in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results.

6. (Original) The method as recited in Claim 1, wherein:

the seeding and the depositing are performed according to an electroless procedure.

7. (Original) The method as recited in Claim 1, wherein:

the firing is performed at a temperature between 830 and 870°C.

8. (Original) The method as recited in Claim 1, wherein:  
the firing is performed at a temperature of 850°C.

9.-10. (Canceled)